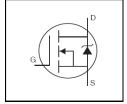


IR MOSFET™

Features

- Advanced Process Technology
- · Dynamic dv/dt Rating
- 175°C Operating Temperature
- Fast Switching
- Fully Avalanche Rated
- Lead-Free



V _{(BR)DSS}	100V
R _{DS(on)} max.	0.036Ω
I _D	42A

Description

IR MOSFET™ technology from Infineon utilizes advanced processing techniques to achieve extremely low on-resistance per silicon area. This benefit, combined with the fast switching speed and rugged device design that IR MOSFET™ devices are well known for, provides the designer with an extremely efficient and reliable device for use in a wide variety of applications.

The TO-247 package is preferred for commercial-industrial applications where higher power levels preclude the use of TO-220 devices. The TO-247 is similar but superior to the earlier TO-218 package because of its isolated mounting hole.



G	D	S
Gate	Drain	Source

Page part number	Pookogo Typo	Standard Pack		Orderable Part Number
Base part number	Package Type	Form	Quantity	Orderable Part Nulliber
IRFP150MPbF	TO-247AD	Tube	25	IRFP150MPbF

Absolute Maximum Ratings

Symbol	Parameter	Max.	Units
I _D @ T _C = 25°C	Continuous Drain Current, V _{GS} @ 10V	42	
I _D @ T _C = 100°C	Continuous Drain Current, V _{GS} @ 10V	30	A
I _{DM}	Pulsed Drain Current ①⑤	140	
$P_D @ T_C = 25^{\circ}C$	Maximum Power Dissipation	160	W
	Linear Derating Factor	1.1	W/°C
V_{GS}	Gate-to-Source Voltage	± 20	V
E _{AS}	Single Pulse Avalanche Energy ②⑤	420	mJ
I _{AR} Avalanche Current ①⑤		22	Α
E _{AR}	Repetitive Avalanche Energy ①	16	mJ
dv/dt	Peak Diode Recovery dv/dt③⑤	5.0	V/ns
T_J	Operating Junction and	-55 to + 175	
T _{STG}	Storage Temperature Range	-55 10 + 175	°C
	Soldering Temperature, for 10 seconds (1.6mm from case)	300	
	Mounting torque, 6-32 or M3 screw	10 lbf•in (1.1N•m)	

Thermal Resistance

Symbol	Parameter	Тур.	Max.	Units
$R_{\theta JC}$	Junction-to-Case		0.95	
$R_{\theta CS}$	Case-to-Sink, Flat, Greased Surface	0.24		°C/W
$R_{\theta,IA}$	Junction-to-Ambient		40	



Electrical characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Тур.	Max.	Units	Conditions
V _{(BR)DSS}	Drain-to-Source Breakdown Voltage	100			V	$V_{GS} = 0V, I_{D} = 250\mu A$
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient		0.11		V/°C	Reference to 25°C, I _D = 1mA ⑤
R _{DS(on)}	Static Drain-to-Source On-Resistance			0.036	Ω	V _{GS} = 10V, I _D = 23A ④
$V_{GS(th)}$	Gate Threshold Voltage	2.0		4.0	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$
gfs	Forward Trans conductance	14			S	$V_{DS} = 25V, I_D = 22A$
ı	Drain-to-Source Leakage Current			25		$V_{DS} = 100V, V_{GS} = 0V$
IDSS	Diam-to-Source Leakage Current			250	μΑ	$V_{DS} = 80V, V_{GS} = 0V, T_{J} = 150^{\circ}C$
	Gate-to-Source Forward Leakage			100	nΛ	$V_{GS} = 20V$
IGSS	Gate-to-Source Reverse Leakage			-100	nA	$V_{GS} = -20V$

Dynamic Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

Q_g	Total Gate Charge	 	110		I _D = 22A
Q_{gs}	Gate-to-Source Charge	 	15	nC	$V_{DS} = 80V$
Q_{gd}	Gate-to-Drain Charge		58		V _{GS} = 10V, See Fig.6 and 13 ④⑤
$t_{d(on)}$	Turn-On Delay Time	 11			$V_{DD} = 50V$
t _r	Rise Time	 56		no	$I_D = 22A$
$t_{d(off)}$	Turn-Off Delay Time	 45		ns	$R_G = 3.6\Omega$
t _f	Fall Time	 40			R _D = 2.3Ω , See Fig.10④⑤
L _D	Internal Drain Inductance	 5.0			Between lead, 6mm (0.25in.)
L _S	Internal Source Inductance	 13		nH	from package and center of die contact
C _{iss}	Input Capacitance	 1900			$V_{GS} = 0V$
C_{oss}	Output Capacitance	 450		рF	$V_{DS} = 25V$
C_{rss}	Reverse Transfer Capacitance	 230			f = 1.0MHz, See Fig.5⑤

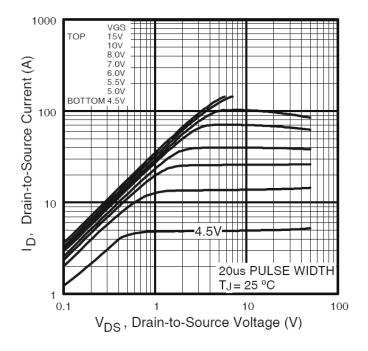
Diode Characteristics

	Parameter	Min.	Тур.	Max.	Units	Conditions
Is	Continuous Source Current (Body Diode)			42		MOSFET symbol showing the
I _{SM}	Pulsed Source Current (Body Diode) ①			140		integral reverse p-n junction diode.
V_{SD}	Diode Forward Voltage			1.3	V	$T_J = 25^{\circ}C, I_S = 23A, V_{GS} = 0V $ ④
t _{rr}	Reverse Recovery Time		180	270	ns	$T_J = 25^{\circ}C$, $I_F = 22A$
Q_{rr}	Reverse Recovery Charge		1.2	1.8	μC	di/dt = 100A/µs ④

Notes

- ① Repetitive rating; pulse width limited by max. junction temperature. (See fig. 11).
- $^{\circ}$ V_{DD} = 25V, T_J = 25°C, L = 1.7mH, R_G = 25 Ω , I_{AS} = 22A.(See fig. 12).
- $\label{eq:local_local_local} \text{\Im} \quad I_{SD} \leq 22A, \; di/dt \leq 180A/\mu s, \; V_{DD} \leq V_{(BR)DSS}, \; T_J \leq 175^{\circ}C.$
- 4 Pulse width $\leq 300 \mu s$; duty cycle $\leq 2\%$.
- ⑤ Uses IRF1310N data and test conditions.





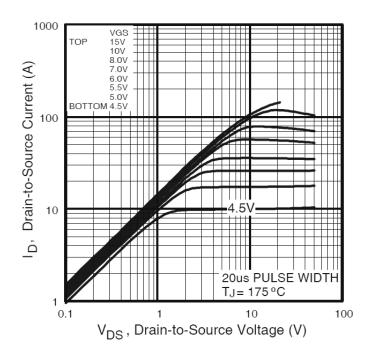
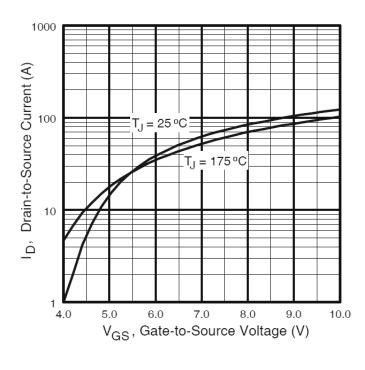


Fig. 1 Typical Output Characteristics

Fig. 2 Typical Output Characteristics





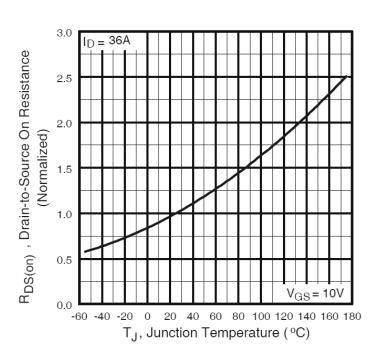
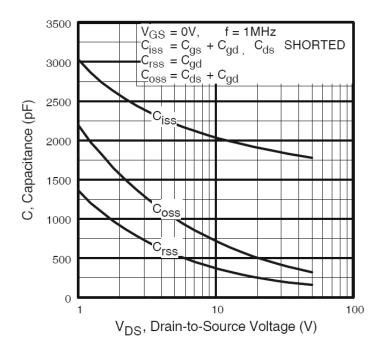


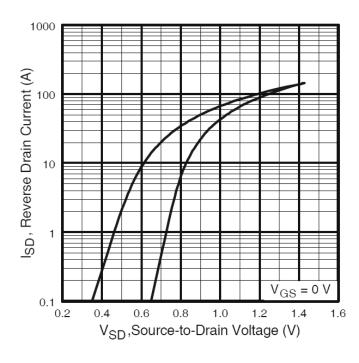
Fig. 4 Normalized On-Resistance vs. Temperature

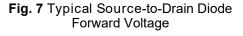


I_D = 22A V_{DS} = 80V V_{DS} = 50V V_{GS}, Gate-to-Source Voltage (V) $V_{DS}^{-3} = 20V$ 16 12 8 FOR TEST CIRCUIT SEE FIGURE 13 0 0 20 40 60 80 100 120 Q_G, Total Gate Charge (nC)

Fig 5. Typical Capacitance vs. Drain-to-Source Voltage

Fig 6. Typical Gate Charge vs. Gate-to-Source Voltage





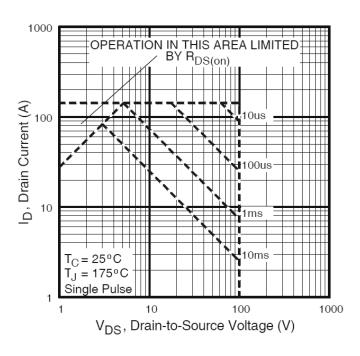


Fig 8. Maximum Safe Operating Area

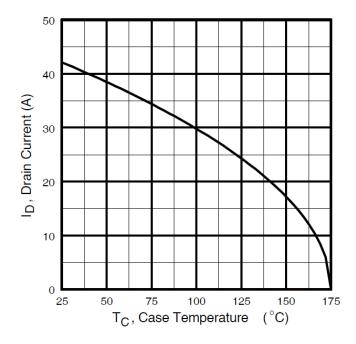


Fig 9. Maximum Drain Current vs. Case Temperature

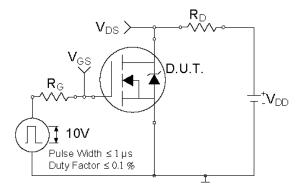


Fig 10a. Switching Time Test Circuit

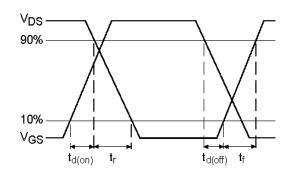


Fig 10a. Switching Time Waveforms

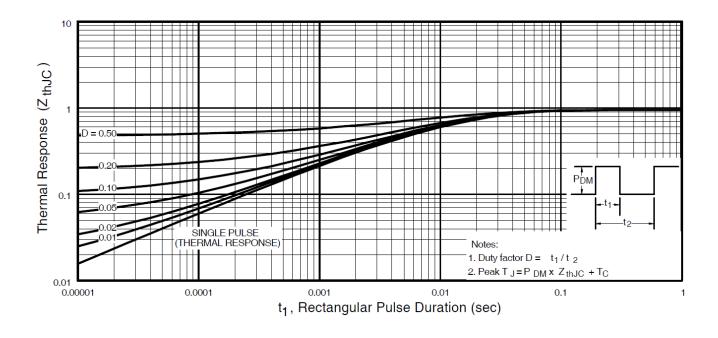


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case



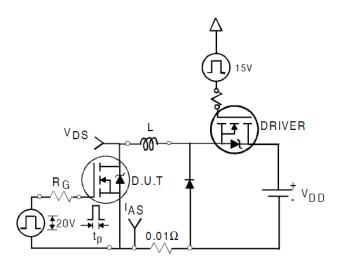


Fig. 12a. Unclamped Inductive Test Circuit

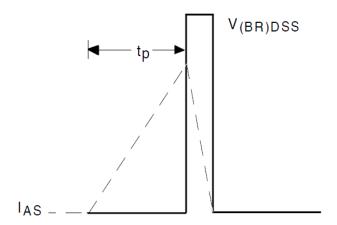


Fig. 12b. Unclamped Inductive Waveforms

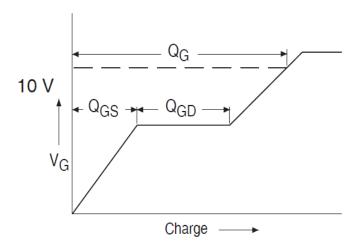


Fig 13a. Basic Gate Charge Waveform

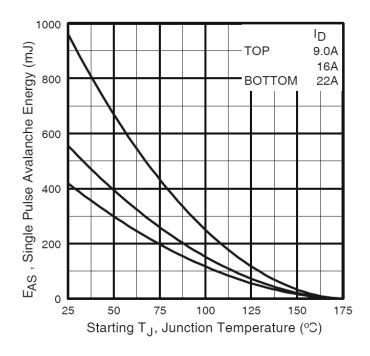


Fig 12c. Maximum Avalanche Energy vs. Drain Current

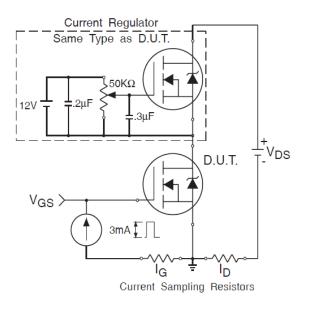
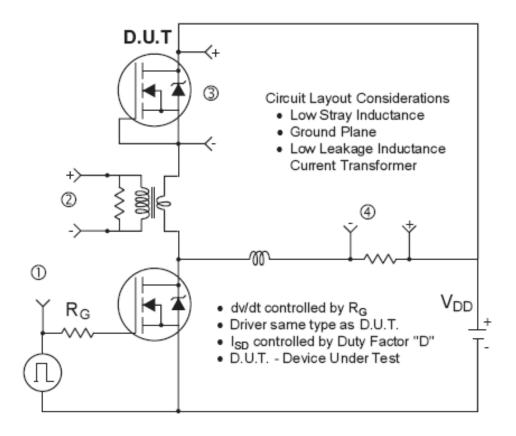


Fig 13b. Gate Charge Test Circuit





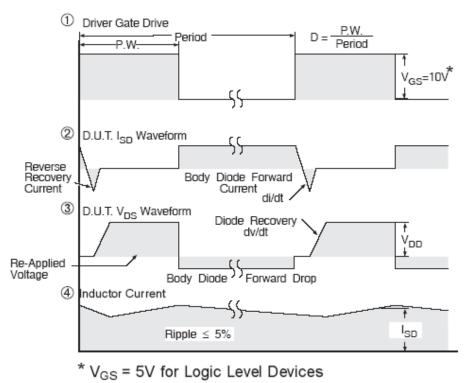
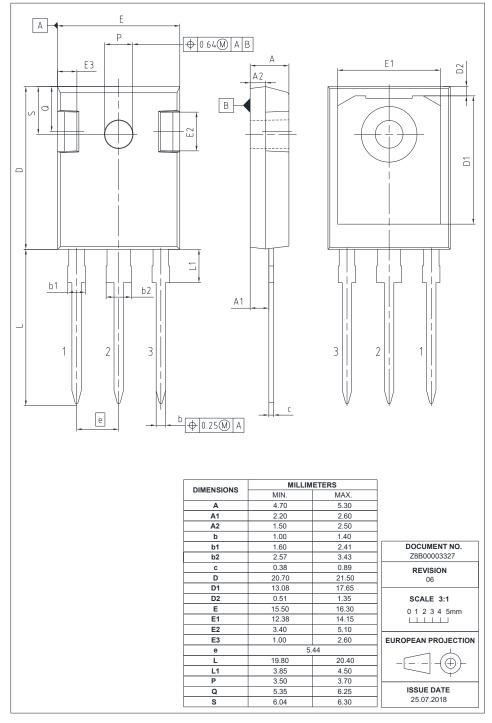


Fig 14. Peak Diode Recovery dv/dt Test Circuit for N-Channel IR MOSFET™



TO-247AD Package Outline (Dimensions are shown in millimeters (inches))



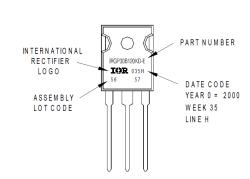
TO-247AD Part Marking Information

EXAMPLE: THIS IS AN IRGP30B120KD-E WITH ASSEMBLY

LOT CODE 5657

ASSEMBLED ON WW 35, 2000 IN THE ASSEMBLY LINE "H"

Note: "P" in assembly line position indicates "Lead-Free"





Revision History

Date	Comments			
	Updated datasheet with corporate template			
05/28/2020	Updated Package picture-page1			
03/20/2020	 Corrected from "Hexfet power MOSFET" to "IR MOSFET™" -page1 &7 			
	Corrected part marking from TO-247AC to TO-247AD on page 8.			

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